APPARATUS FOR DETECTING MICRO-CRACKS IN WAFERS AND METHOD THEREFOR

Abstract

A method and apparatus for wafer inspection is disclosed. The method and apparatus involve directing light substantially along a first axis towards a first surface of a wafer to thereby obtain light emanating along the first axis from a second surface of the wafer, wherein the first and second surfaces of the wafer are substantially outwardly opposing and substantially extending parallel to a plane. The method and apparatus further involve directing light substantially along a second axis towards the first surface of the wafer to thereby obtain light emanating along the second axis from the second surface of the wafer, the first axis being angled away from the second axis about a reference axis extending along the plane. More specifically, the orthographic projection of the first axis on the plane is substantially parallel to the orthographic projection of the second axis on the plane, and each the orthographic projections of the first and second axes on the plane is substantially orthogonal to the reference axis.

FIG. 11